

TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM767705

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|---|--------------------------------------|-----------------------|-------------------------|
| SUBMISSION TYPE: | NEW ASSIGNMENT | | |
| NATURE OF CONVEYANCE: | RELEASE OF SECURITY INTEREST | | |
| CONVEYING PARTY DATA | | | |
| Name | Formerly | Execution Date | Entity Type |
| SILICON VALLEY BANK | | 11/14/2022 | Corporation: CALIFORNIA |
| RECEIVING PARTY DATA | | | |
| Name: | MOVELLA INC. | | |
| Street Address: | 2750 N. 1st St., Ste 300 | | |
| City: | San Jose | | |
| State/Country: | CALIFORNIA | | |
| Postal Code: | 95131 | | |
| Entity Type: | Corporation: DELAWARE | | |
| PROPERTY NUMBERS Total: 4 | | | |
| Property Type | Number | Word Mark | |
| Serial Number: | 88491567 | SENSFIT | |
| Registration Number: | 4700413 | MCUBE | |
| Registration Number: | 4254341 | MCUBE | |
| Registration Number: | 4659788 | MCUBE | |
| CORRESPONDENCE DATA | | | |
| Fax Number: | | | |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> | | | |
| Phone: | 4159831234 | | |
| Email: | sdipdocket@pillsburylaw.com | | |
| Correspondent Name: | Sam E. Iverson | | |
| Address Line 1: | Four Embarcadero Center, 22nd Floor | | |
| Address Line 4: | San Francisco, CALIFORNIA 94111-5998 | | |
| NAME OF SUBMITTER: | Sam E. Iverson | | |
| SIGNATURE: | /Sam E. Iverson/ | | |
| DATE SIGNED: | 11/14/2022 | | |
| Total Attachments: 17 | | | |
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RELEASE OF INTELLECTUAL PROPERTY SECURITY AGREEMENT

THIS RELEASE OF INTELLECTUAL PROPERTY SECURITY AGREEMENT (“**Release**”) is made as of November 14, 2022, between MOVELLA INC., a Delaware corporation (formerly known as MCUBE, INC.) with its principal office at 2570 N. 1st St., Ste 300, San Jose, CA 95131 (“**Grantor**”), and SILICON VALLEY BANK, a California corporation, with its principal office located at 3003 Tasman Drive, Santa Clara, California 95054 (the “**Bank**”).

RECITALS

WHEREAS, in connection with certain loan documents, Bank and Grantor, and the other borrowers party thereto, entered into that certain Amended and Restated Loan and Security Agreement dated as of August 10, 2018 (as amended, supplemented, or otherwise modified from time to time, the “**Loan Agreement**”) and that certain Second Amendment to Amended and Restated Loan and Security Agreement dated as of June 8, 2020, by and between Bank and Grantor, and the other borrowers party thereto, (the “**Second Amendment**”);

WHEREAS, pursuant to and in conjunction with the Second Amendment and the Loan Agreement, Grantor executed and delivered to the Bank an Intellectual Property Security Agreement dated as of June 8, 2020 (the “**IP Agreement**”), which IP Agreement was recorded with the United States Patent and Trademark Office (“**USPTO**”) on June 11, 2020, in Reel 6963, Frame 0689, and Reel 52909, Frame 0119 for the purpose of securing certain obligations of Grantor to Bank;

WHEREAS, pursuant to and in conjunction with the Second Amendment and the Loan Agreement, and IP Agreement, Grantor granted Bank, for the benefit of Bank, a security interest in all of Grantor’s right, title and interest in and to the Intellectual Property Collateral (as defined in the IP Agreement)], including, without limitation, the Copyrights identified on Exhibit A attached hereto, Patents identified on Exhibit B attached hereto and the Trademarks identified on Exhibit C attached hereto (collectively, the “**Released Intellectual Property**”), and pledged and mortgaged (but did not transfer title to) such Intellectual Property to Bank; and

WHEREAS, the Bank acknowledges and agrees that the Loan Agreement and Second Amendment have been terminated or expired and has agreed to terminate, cancel, discharge and release all of its rights in the Released Intellectual Property secured by the Loan Agreement, the Second Amendment, and the IP Agreement, including, without limitation, reconveyance of any and all of the rights and interests of Bank that were pledged and mortgaged (but without the transfer of title) in and to the Released Intellectual Property to Grantor.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, and intending to be legally bound, and pursuant to the terms and conditions set forth in this Release, Grantor hereby agrees as follows:

1. DEFINED TERMS. All capitalized terms used but not otherwise defined herein have the meanings given to them in the Loan Agreement, Second Amendment and IP Agreement.

2. TERMINATION AND RELEASE OF GRANT OF SECURITY INTEREST IN INTELLECTUAL PROPERTY COLLATERAL. Effective as of the date set forth above, Bank hereby terminates and releases in its entirety all security interests in the Released Intellectual

Property, including the lien and security interest, granted pursuant to the IP Agreement, and Bank hereby assigns, reconveys and transfers to Grantor, without any representation, warranty, or recourse whatsoever, Bank's entire right, title, claim and interest in and to the Released Intellectual Property.

3. RECORDATION. Bank hereby authorizes and requests the Commissioner for Patents, the Commissioner for Trademarks, and the Register of Copyrights and any other government officials of the United States to record this Release, as applicable.

4. FURTHER ASSURANCE. The Bank hereby agrees to, at the sole expense of Grantor, duly execute, acknowledge, procure and deliver any further documents, including, but not limited to, those documents necessary under Article 9 of the Uniform Commercial Code or other applicable law, and to do such other acts as may be reasonable necessary to effect the release of the lien and security interest in the Released Intellectual Property contemplated hereby.

5. MODIFICATION. This Release may not be modified, nor may any provision hereof be waived, orally or in any manner other than by an agreement in writing signed by the parties hereto or their respective successors and assigns.

6. GOVERNING LAW. This Release and any claim, controversy, dispute or cause of action (whether in contract or tort or otherwise) based upon, arising out of or relating to this Release and the transactions contemplated hereby and thereby shall be governed by, and construed in accordance with, the laws of the United States and the State of California, without giving effect to any choice or conflict of law provision or rule (whether of the State of California or any other jurisdiction).

7. EXECUTION. Delivery of an executed signature page to this Release by facsimile or electronic transmissions (including .pdf file or Docu sign) shall be effective as delivery of an original signature.

(Signature follows on next page)

IN WITNESS WHEREOF, the Bank has caused this Release to be duly executed and delivered by its duly authorized office as of the date first written above.

SILICON VALLEY BANK, as Bank

By: DocuSigned by: Nina Davies
Name: 162ECCE8F99E4C6... Nina Davies
Title: Vice President

EXHIBIT A

Copyrights

| Description | Registration/ Application <u>Number</u> | Registration/ Application <u>Date</u> |
|-------------|--|--|
| None | | |

EXHIBIT B

Patents

| No. | Description | Registration/ Application Number | Registration/ Application Date |
|-----|---|-------------------------------------|-----------------------------------|
| 1. | Three Axis Magnetic Sensor Device and Method | 8,742,520 | 6/3/2014 |
| 2. | Method and Structure of Integrated Micro Electro-Mechanical Systems and Electronic Devices Using Edge Bond Pads | 8,592,993 | 11/26/2013 |
| 3. | Method and Structure of Sensors or Electronic Devices Using Vertical Mounting | 8,749,004 | 6/10/2014 |
| 4. | Method and Structure of Sensors and MEMS Devices Using Vertical Mounting with Interconnections | 8,981,560 | (03/17/2015 |
| 5. | Low Power Rotational Detection Methods and Apparatus | 16/101,276 | 8/10/2018 |
| 6. | MEMS Device with Stiction Recover and Methods | 15/877,999 | 1/23/2018 |
| 7. | Differential MEMS Device and Methods | 16/530,923 | (08/02/2019 |

| No. | Description | Registration/ Application <u>Number</u> | Registration/ Application <u>Date</u> |
|-----|---|--|--|
| 8. | Portable Computing Device and Methods | 16/655,124 | 10/16/2019 |
| 9. | Flexible Sensor System and Methods | 16/734,234 | 1/4/2019 |
| 10. | Device and Method for Using Time Rate of Change of Sensor Data to Determine Device Rotation | 10,197,587 | 2/5/2019 |
| 11. | Dynamic Offset Correction for Calibration of MEMS Sensor | 10,324,108 | 6/18/2019 |
| 12. | Three Axis Magnetic Sensor Device and Method | 8,486,723 | 7/16/2013 |
| 13. | Accurate Gyroscope Device Using MEMS and Quartz | 8,584,521 | 11/19/2013 |
| 14. | Touchscreen Operation Threshold Methods and Apparatus | 8,643,612 | 2/4/2014 |
| 15. | Analog Touchscreen Methods and Apparatus | 8,797,279 | 8/5/2014 |

| No. | Description | Registration/ Application <u>Number</u> | Registration/ Application <u>Date</u> |
|-----|---|--|--|
| 16. | MEMS-Based Dual and Single Proof-Mass Accelerometer Methods and Apparatus | 9,246,017 | 1/26/2016 |
| 17. | Selective Accelerometer Data Processing Methods and Apparatus | 9,335,845 | 5/10/2016 |
| 18. | Security System and Methods for Integrated Devices | 9,418,247 | 8/16/2016 |
| 19. | Three Axis Magnetic Sensor Device and Method Using Flex Cables | 9,423,473 | 8/23/2016 |
| 20. | Method of Reducing Gyroscope Oscillator Start-Up Time and Device Therefor | 9,464,899 | 10/11/2016 |
| 21. | Method and Device for Magnetoresistive Sensor | 9,588,194 | 3/7/2017 |
| 22. | Method and Structure of Three Dimensional CMOS Transistors with Hybrid Crystal Orientations | 9,595,479 | 3/14/2017 |
| 23. | Method and Device for Calibrating a Magnetometer Using Partial Sampling | 9,677,906 | 6/13/2017 |

| No. | Description | Registration/ Application <u>Number</u> | Registration/ Application <u>Date</u> |
|-----|--|--|--|
| 24. | Dual Accelerometer Plus Magnetometer Body Rotation Rate Sensor-Gyrometer | 13/758,381 | 2/4/2013 |
| 25. | Method of Fabricating MEMS Devices Using Plasma Etching and Device Thereof | 14/658,114 | 3/13/2015 |
| 26. | Security System and Methods for Integrated Devices | 10,078,112 | 9/18/2018 |
| 27. | Multi-Layer Single Chip MEMS WLCSP Fabrication | 10,106,399 | 10/23/2018 |
| 28. | Method and Apparatus for Real-Time Motion Direction Detection via Acceleration-Magnetic Fusion | 10,175,778 | 1/8/2019 |
| 29. | MEMS Device with Reduced Dynamic Stress and Methods | 10,322,926 | 6/18/2019 |
| 30. | Umbrella, Umbrella Peripheral and Methods | 10,561,210 | 2/18/2020 |
| 31. | Multiple MEMS Device and Methods | 10,605,823 | 3/31/2020 |

| No. | Description | Registration/ Application <u>Number</u> | Registration/ Application <u>Date</u> |
|-----|--|--|--|
| 32. | Method and Apparatus for Patterning Micro and Nano Structures Using a Mask-Less Process | 7,473,912 | 1/6/2009 |
| 33. | Method and Structure for an Out-of-Plane Compliant Micro Actuator | 7,498,715 | 3/3/2009 |
| 34. | Method and Structure for Kinetic Energy Based Generator for Portable Electronic Devices | 7,608,933 | 10/27/2009 |
| 35. | Method and Structure for an Out-of-Plane Compliant Micro Actuator | 7,928,632 | 4/19/2011 |
| 36. | Method and Structure of Monolithically Integrated IC-MEMS Oscillator Using IC Foundry-Compatible Processes | 8,071,398 | 12/6/2011 |
| 37. | Method and Structure of Monolithically Integrated Infrared Sensing Device | 8,120,076 | 2/21/2012 |
| 38. | Method and Structures of Monolithically Integrated ESD Suppression Device | 8,148,781 | 4/3/2012 |
| 39. | Methods and Apparatus for Facilitating Capture of Magnetic Credit Card Data on a Hand Held Device | 8,181,874 | 5/22/2012 |

| No. | Description | Registration/ Application <u>Number</u> | Registration/ Application <u>Date</u> |
|-----|---|--|--|
| 40. | Method and Structure of Monolithically Integrated Inertial Sensor Using IC Foundry-Compatible Process | 8,227,285 | 7/24/2012 |
| 41. | Method and Structure of Wafer Level Encapsulation of Integrated Circuits with Cavity | 8,227,911 | 7/24/2012 |
| 42. | Foundry Compatible Process for Manufacturing a Magneto Meter Using Lorentz Force for Integrated Systems | 8,236,577 | 8/7/2012 |
| 43. | Methods and Apparatus for Capturing Magnetic Credit Card Data on a Hand Held Device | 8,245,923 | 8/21/2012 |
| 44. | Method and Structure of an Integrated CMOS and MEMS Device Using Air Dielectric | 8,324,047 | 12/4/2012 |
| 45. | Method and Structure of Integrated Micro Electro-Mechanical Systems and Electronic Devices Using Edge Bond Pads | 8,367,522 | 2/5/2013 |
| 46. | Integrated MEMS and CMOS Package and Method | 8,395,252 | 3/12/2013 |
| 47. | Magneto Meter Using Lorentz Force for Integrated Systems | 8,402,666 | 3/26/2013 |

| No. | Description | Registration/ Application <u>Number</u> | Registration/ Application <u>Date</u> |
|-----|---|--|--|
| 48. | Multiple Magneto Meters Using Lorentz Force for Integrated Systems | 8,407,905 | 4/2/2013 |
| 49. | Integrated CMOS and MEMS with Air Dielectric Method and System | 8,421,082 | 4/16/2013 |
| 50. | Method and Structure of Monolithically Integrated Inertial Sensor Using IC Foundry-Compatible Processes | 8,432,005 | 4/30/2013 |
| 51. | Method and Structure of Sensors or Electronic Devices Using Vertical Mounting | 8,476,084 | 7/2/2013 |
| 52. | Method and Structure of Sensors and MEMS Devices Using Vertical Mounting with Interconnections | 8,476,129 | 7/2/2013 |
| 53. | Method and Structure of Monolithically Integrated Microneedle Biochip | 8,506,529 | 8/13/2013 |
| 54. | Anchor Design and Method for MEMS Transducer Apparatuses | 8,553,389 | 10/8/2013 |
| 55. | Package Tolerate Design and Method | 8,564,075 | 10/22/2013 |

| No. | Description | Registration/ Application <u>Number</u> | Registration/ Application <u>Date</u> |
|-----|--|--|--|
| 56. | Method and Structure of Wafer Level Encapsulation of Integrated Circuits with Cavity | 8,569,180 | 10/29/2013 |
| 57. | Multi-Axis Integrated MEMS Devices with CMOS Circuits and Method Therefor | 8,637,943 | 1/28/2014 |
| 58. | Methods and Structure for Adapting MEMS Structures to Form Electrical Interconnections for Integrated Circuits | 8,652,961 | 2/18/2014 |
| 59. | Method and Structure of Monolithically Integrated IC-MEMS Oscillator Using IC Foundry-Compatible Processes | 8,704,238 | 4/22/2014 |
| 60. | Method and Structure for Adding Mass with Stress Isolation to MEMS Structures | 8,710,597 | 4/29/2014 |
| 61. | Methods and Apparatus for Initiating Image Capture on a Hand-Held Device | 8,723,986 | 5/13/2014 |
| 62. | Integrated Inertial Sensing Apparatus Using MEMS and Quartz Configured on Crystallographic Planes | 8,794,065 | 8/5/2014 |
| 63. | Method and Structure of Monolithically Integrated Pressure Sensor Using IC Foundry-Compatible Processes | 8,796,746 | 8/5/2014 |

| No. | Description | Registration/ Application <u>Number</u> | Registration/ Application <u>Date</u> |
|-----|--|--|--|
| 64. | Method and Structure of Monolithically Integrated Micromachined Microphone Using IC Foundry-Compatible Processes | 8,796,790 | 8/5/2014 |
| 65. | Integrated System on Chip Using Multiple MEMS and CMOS Devices | 8,823,007 | 9/2/2014 |
| 66. | Methods and Apparatus for Object Tracking on a Hand-Held Device | 8,928,602 | 1/6/2015 |
| 67. | Methods and Apparatus for Operating Hysteresis on a Hand Held Device | 8,928,696 | 1/6/2015 |
| 68. | Integrated RF MEMS, Control Systems and Methods | 8,936,959 | 1/20/2015 |
| 69. | Three Axis Magnetic Sensor Device and Method Using Flex Cables | 8,969,101 | 3/3/2015 |
| 70. | Oxide Retainer Method for MEMS Devices | 8,993,362 | 3/31/2015 |
| 71. | Method and Structure of Monolithically Integrated ESD Suppression Device | 8,999,835 | 4/7/2015 |

| No. | Description | Registration/ Application <u>Number</u> | Registration/ Application <u>Date</u> |
|-----|---|--|--|
| 72. | Multi-Axis Integrated MEMS Devices with CMOS Circuits and Methods Therefor | 9,150,406 | 10/6/2015 |
| 73. | Distributed MEMS Devices Time Synchronization Methods and System | 9,174,838 | 11/3/2015 |
| 74. | Substrate Curvature Compensation Methods and Apparatus | 9,291,638 | 3/22/2016 |
| 75. | Method and Structure for Adding Mass with Stress Isolation to MEMS Structures | 9,321,629 | 4/26/2016 |
| 76. | Method and Structure of Monolithically Integrated Absolute Pressure Sensor | 9,340,414 | 5/17/2016 |
| 77. | Integrated CMOS and MEMS Devices with Air Dielectrics | 9,365,412 | 6/14/2016 |
| 78. | Method for Fabricating a Transducer Apparatus | 9,376,312 | 6/28/2016 |
| 79. | System on a Chip Using Integrated MEMS and CMOS Devices | 9,440,846 | 9/13/2016 |

| No. | Description | Registration/ Application <u>Number</u> | Registration/ Application <u>Date</u> |
|-----|--|--|--|
| 80. | Method and Structure of MEMS WLCSP Fabrication | 9,540,232 | 1/10/2017 |
| 81. | Power Saving Method of Operating a Portable Computing Device | 9,588,569 | 3/7/2017 |
| 82. | Single Point Offset Calibration for Inertial Sensors | 9,594,095 | 3/14/2017 |
| | | | |
| 83. | MEMS-Based Proximity Sensor Device and Method | 9,696,337 | 7/4/2017 |
| | | | |
| 84. | System Configured for Integrated Communication, MEMS, Processor, and Applications Using a Foundry Compatible Semiconductor Process | 9,709,509 | 7/18/2017 |
| 85. | Method and Structure of MEMS PLCSP Fabrication | 9,738,510 | 8/22/2017 |

| No. | Description | Registration/ Application <u>Number</u> | Registration/ Application <u>Date</u> |
|-----|--|--|--|
| 86. | Method and Structure of MEMS PLCSP Fabrication | 9,975,759 | 5/22/2018 |
| 87. | Selective Accelerometer Data Processing Methods and Apparatus | 13/437,914 | 4/2/2012 |
| 88. | Methods and Apparatus for Mobile Device Power Management Using Accelerometer Data | 13/759,027 | 2/4/2013 |
| 89. | Dynamic Temperature Calibration | 13/940,199 | 7/11/2013 |
| 90. | Tower-Shaped Supporting Structure | 14/233,903 | 1/21/2014 |
| 91. | System on a Chip Using Integrated MEMS and CMOS Devices | PCT US2010054567 | 10/28/2010 |

EXHIBIT C

Trademarks

| No. | Description | Registration/ Serial Number | Registration/ Application Date |
|-----|------------------|-----------------------------------|--------------------------------------|
| 1. | SENSFIT | 88/491,567 | 06/27/2019 |
| 2. | MCUBE (& design) | 4,700,413 | 03/10/2015 |
| 3. | MCUBE | 4,254,341 | 12/04/2012 |
| 4. | MCUBE | 4,659,788 | 12/23/2014 |